

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>LI-TING WANG</td> <td>02/25/2014</td> </tr> <tr> <td>TENG-CHUN TSAI</td> <td>02/25/2014</td> </tr> <tr> <td>CHENG-TUNG LIN</td> <td>02/25/2014</td> </tr> <tr> <td>HUNG-TA LIN</td> <td>03/03/2014</td> </tr> <tr> <td>HUICHENG CHANG</td> <td>03/04/2014</td> </tr> </tbody> </table>		Name	Execution Date	LI-TING WANG	02/25/2014	TENG-CHUN TSAI	02/25/2014	CHENG-TUNG LIN	02/25/2014	HUNG-TA LIN	03/03/2014	HUICHENG CHANG	03/04/2014
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>HSIN-CHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	HSIN-CHU SCIENCE PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA													
Fax Number:	(216)502-0601												
Phone:	216-502-0600												
Email:	docketing@eschweilerlaw.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.												
Address Line 1:	629 EUCLID AVENUE, SUITE 1000												
Address Line 2:	NATIONAL CITY BANK BUILDING												
Address Line 4:	CLEVELAND, OHIO 44114												
ATTORNEY DOCKET NUMBER:	TSMCP394US												

NAME OF SUBMITTER:	THOMAS G. ESCHWEILER
Signature:	/Thomas G. Eschweiler/
Date:	03/06/2014
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U.S. Patent Appln. No.

Docket No. TSMCP394US

Filing Date

**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):

Li-Ting Wang  
11F., No.39, Ln. 19, Guanxin Rd.  
East Dist., Hsinchu City  
300, Taiwan (R.O.C.)

Assignor(s):

Teng-Chun Tsai  
11 F No.188, Guanxin W. St.  
East Dist., Hsinchu City  
Taiwan (R.O.C.)

Assignor(s):

Cheng-Tung Lin  
5F., No.6, Alley 39, Lane 152, Sec. 2, Jhongsing Rd.  
Jhudong Township, Hsinchu County  
310, Taiwan (R.O.C.)

Assignor(s):

Hung-Ta Lin  
No.7, Lane 6, Ankang St.  
East District, Hsinchu City  
300, Taiwan (R.O.C.)

Assignor(s):

Huicheng Chang  
No.11, Ln. 220, Xinglong St.  
Guantian Dist., Tainan City  
720, Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.  
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park  
Hsin-Chu, Taiwan 300-77  
Republic of China

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Docket No. TSMCP394US

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**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

**"CONTACTS FOR TRANSISTORS"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and

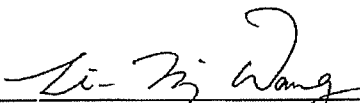
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continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 02/25/2014  
Date

✓   
Name 1<sup>st</sup> Inventor Li-Ting Wang

U.S. Patent Appln. No.  
Filing Date

TSMC Docket No. TSMC2013-1745  
Docket No. TSMCP394US

✓ 02/25/2014  
Date

✓ Teng-Chun Tsai  
Name 2<sup>nd</sup> Inventor Teng-Chun Tsai

TSMC Docket No. TSMC2013-1745

Docket No. TSMCP394US

U.S. Patent Appln. No.

Filing Date

✓ 02/25/2014  
Date

✓ Cheng-Tung Lin  
Name 3<sup>rd</sup> Inventor Cheng-Tung Lin

TSMC Docket No. TSMC2013-1745

Docket No. TSMCP394US

U.S. Patent Appln. No.

Filing Date

✓ 03/03/2014  
Date

✓ Hungta Lin  
Name 4<sup>th</sup> Inventor Hung-Ta Lin



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Filing Date

TSMC Docket No. TSMC2013-1745  
Docket No. TSMCP394US

✓ 3/4/2014  
Date

✓ Huicheng Chang  
Name 5<sup>th</sup> Inventor Huicheng Chang